

# MC14043B, MC14044B

## CMOS MSI

### Quad R–S Latches

The MC14043B and MC14044B quad R–S latches are constructed with MOS P–Channel and N–Channel enhancement mode devices in a single monolithic structure. Each latch has an independent Q output and set and reset inputs. The Q outputs are gated through three–state buffers having a common enable input. The outputs are enabled with a logical “1” or high on the enable input; a logical “0” or low disconnects the latch from the Q outputs, resulting in an open circuit at the Q outputs.

#### Features

- Double Diode Input Protection
- Three–State Outputs with Common Enable
- Outputs Capable of Driving Two Low–power TTL Loads or One Low–Power Schottky TTL Load Over the Rated Temperature Range
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- These Devices are Pb–Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable

#### MAXIMUM RATINGS (Voltages Referenced to $V_{SS}$ )

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	–0.5 to +18.0	V
$V_{in}, V_{out}$	Input or Output Voltage Range (DC or Transient)	–0.5 to $V_{DD} + 0.5$	V
$I_{in}, I_{out}$	Input or Output Current (DC or Transient) per Pin	$\pm 10$	mA
$P_D$	Power Dissipation, per Package (Note 1)	500	mW
$T_A$	Ambient Temperature Range	–55 to +125	°C
$T_{stg}$	Storage Temperature Range	–65 to +150	°C
$T_L$	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### 1. Temperature Derating:

Plastic “P and D/DW” Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

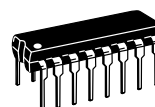
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



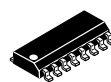
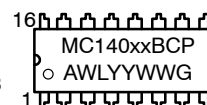
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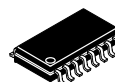
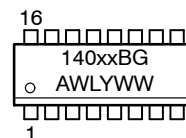
#### MARKING DIAGRAMS



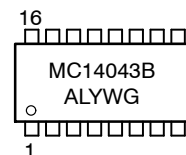
PDIP–16  
P SUFFIX  
CASE 648



SOIC–16  
D SUFFIX  
CASE 751B



SOEIAJ–16  
F SUFFIX  
CASE 966



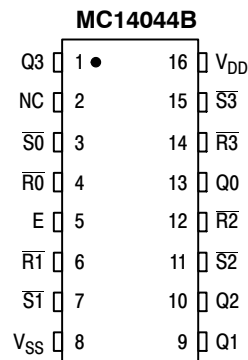
xx = Specific Device Code  
A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G = Pb–Free Indicator

#### ORDERING INFORMATION

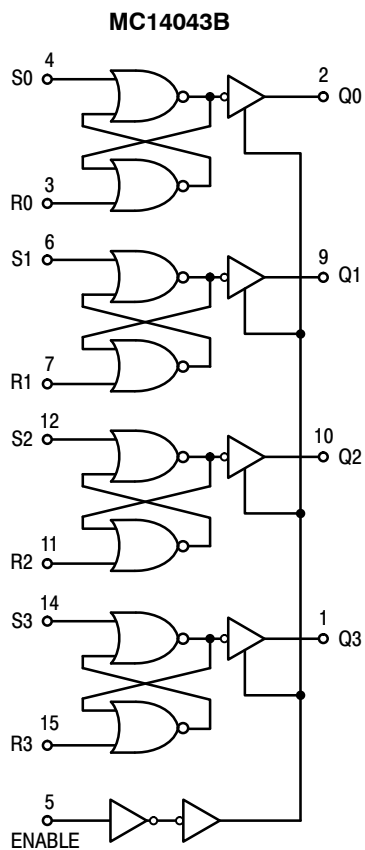
See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

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## PIN ASSIGNMENT



NC = NO CONNECTION

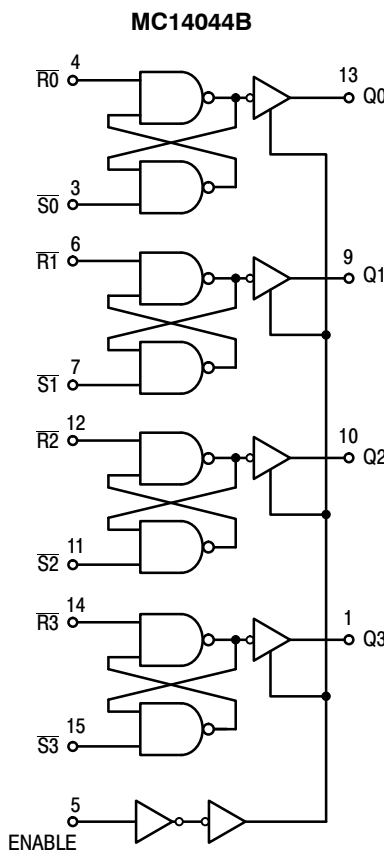


V<sub>DD</sub> = PIN 16  
V<sub>SS</sub> = PIN 8  
NC = PIN 13

### TRUTH TABLE

S	R	E	Q
X	X	0	High Impedance
0	0	1	No Change
0	1	1	0
1	0	1	1
1	1	1	1

X = Don't Care



V<sub>DD</sub> = PIN 16  
V<sub>SS</sub> = PIN 8  
NC = PIN 2

### TRUTH TABLE

S	R	E	Q
X	X	0	High Impedance
0	0	1	0
0	1	1	1
1	0	1	0
1	1	1	No Change

X = Don't Care

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## ELECTRICAL CHARACTERISTICS (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>DD</sub> Vdc	- 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level V <sub>OL</sub>	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
		10	-	0.05	-	0	0.05	-	0.05	
15		-	0.05	-	0	0.05	-	0.05		
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level V <sub>OH</sub>	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
		10	9.95	-	9.95	10	-	9.95	-	
		15	14.95	-	14.95	15	-	14.95	-	
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level V <sub>IL</sub>	5.0	-	1.5	-	2.25	1.5	-	1.5	Vdc
		10	-	3.0	-	4.50	3.0	-	3.0	
15		-	4.0	-	6.75	4.0	-	4.0		
(V <sub>O</sub> = 0.5 or 4.5 Vdc) (V <sub>O</sub> = 1.0 or 9.0 Vdc) (V <sub>O</sub> = 1.5 or 13.5 Vdc)	"1" Level V <sub>IH</sub>	5.0	3.5	-	3.5	2.75	-	3.5	-	Vdc
		10	7.0	-	7.0	5.50	-	7.0	-	
		15	11	-	11	8.25	-	11	-	
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source I <sub>OH</sub>	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc
		5.0	-0.64	-	-0.51	-0.88	-	-0.36	-	
10		-1.6	-	-1.3	-2.25	-	-0.9	-		
15		-4.2	-	-3.4	-8.8	-	-2.4	-		
(V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	Sink I <sub>OL</sub>	5.0	0.64	-	0.51	0.88	-	0.36	-	mAdc
		10	1.6	-	1.3	2.25	-	0.9	-	
		15	4.2	-	3.4	8.8	-	2.4	-	
Input Current	I <sub>in</sub>	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0	-	1.0	-	0.002	1.0	-	30	μAdc
		10	-	2.0	-	0.004	2.0	-	60	
		15	-	4.0	-	0.006	4.0	-	120	
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs all buffers switching)	I <sub>T</sub>	5.0 10 15	I <sub>T</sub> = (0.58 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (1.15 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (1.73 μA/kHz) f + I <sub>DD</sub>						μAdc	
Three-State Output Leakage Current	I <sub>TL</sub>	15	-	± 0.1	-	± 0.0001	± 0.1	-	± 3.0	μAdc

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.004.

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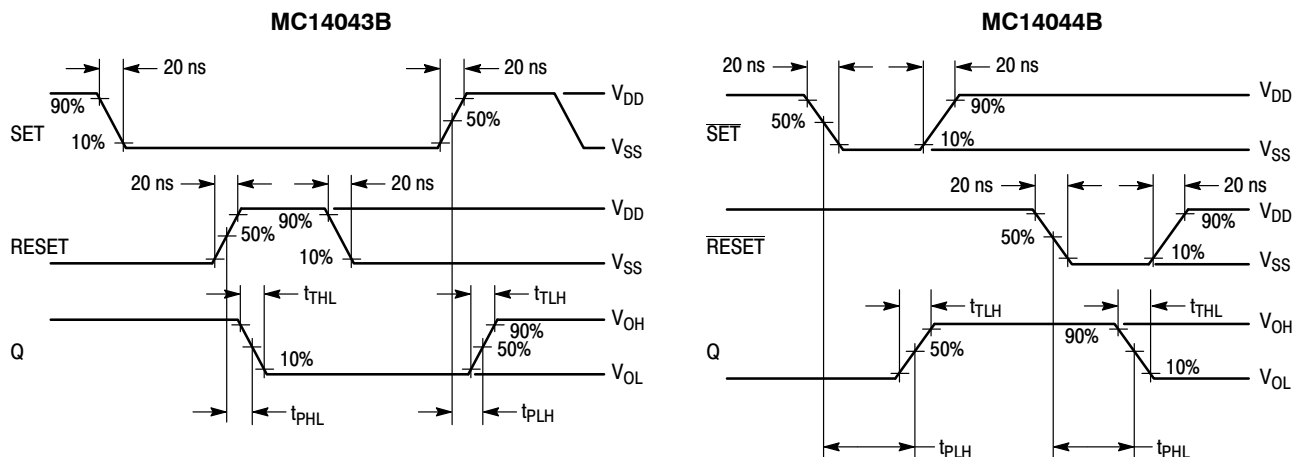
## SWITCHING CHARACTERISTICS (Note 5) ( $C_L = 50 \text{ pF}$ , $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time $t_{TLH} = (1.35 \text{ ns/pF}) C_L + 32.5 \text{ ns}$ $t_{TLH} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$	$t_{TLH}$	5.0 10 15	– – –	100 50 40	200 100 80	ns
Output Fall Time $t_{THL} = (1.35 \text{ ns/pF}) C_L + 32.5 \text{ ns}$ $t_{THL} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{THL} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$	$t_{THL}$	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time $t_{PLH} = (0.90 \text{ ns/pF}) C_L + 130 \text{ ns}$ $t_{PLH} = (0.36 \text{ ns/pF}) C_L + 57 \text{ ns}$ $t_{PLH} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$ $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 130 \text{ ns}$ $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 57 \text{ ns}$ $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$	$t_{PLH}$    $t_{PHL}$	5.0 10 15  5.0 10 15	– – –  – – –	175 75 60  175 75 60	350 175 120  350 175 120	ns    ns
Set, $\overline{\text{Set}}$ Pulse Width	$t_W$	5.0 10 15	200 100 70	80 40 30	– – –	ns
Reset, $\overline{\text{Reset}}$ Pulse Width	$t_W$	5.0 10 15	200 100 70	80 40 30	– – –	ns
Three-State Enable/Disable Delay	$t_{PLZ}$ , $t_{PHZ}$ , $t_{PZL}$ , $t_{PZH}$	5.0 10 15	– – –	150 80 55	300 160 110	ns

5. The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

## AC WAVEFORMS

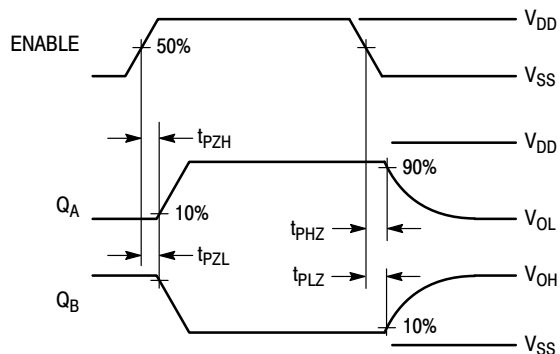
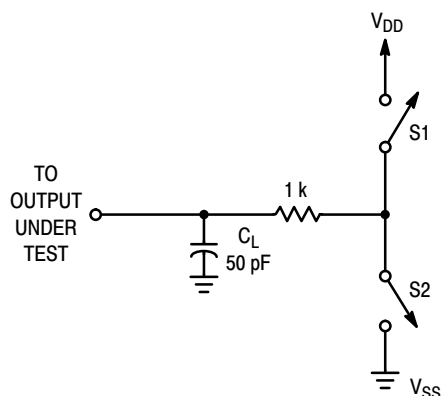


# MC14043B, MC14044B

## THREE-STATE ENABLE/DISABLE DELAYS

### Set, Reset, Enable, and Switch Conditions for 3-State Tests

Test	Enable	S1	S2	Q	MC14043B		MC14044B	
					S	R	$\bar{S}$	$\bar{R}$
t <sub>PZH</sub>	↗	Open	Closed	A	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>
t <sub>PZL</sub>	↘	Closed	Open	B	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DD</sub>	V <sub>SS</sub>
t <sub>PHZ</sub>	↘	Open	Closed	A	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>
t <sub>PLZ</sub>	↗	Closed	Open	B	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DD</sub>	V <sub>SS</sub>



### ORDERING INFORMATION

Device	Package	Shipping†
MC14043BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14043BDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14043BDG*		
MC14043BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14043BDR2G*		
MC14043BFELG	SOEIAJ-16	2000 Units / Tape & Reel
MC14044BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14044BDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14044BDG*		
MC14044BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14044BDR2G*		

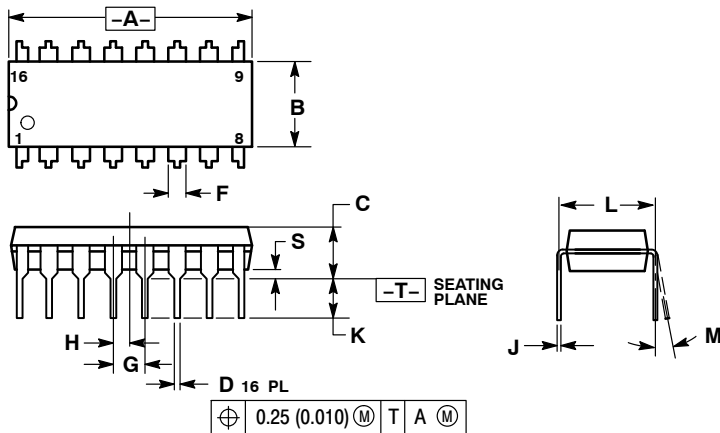
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

# MC14043B, MC14044B

## PACKAGE DIMENSIONS

PDIP-16  
P SUFFIX  
PLASTIC DIP PACKAGE  
CASE 648-08  
ISSUE T

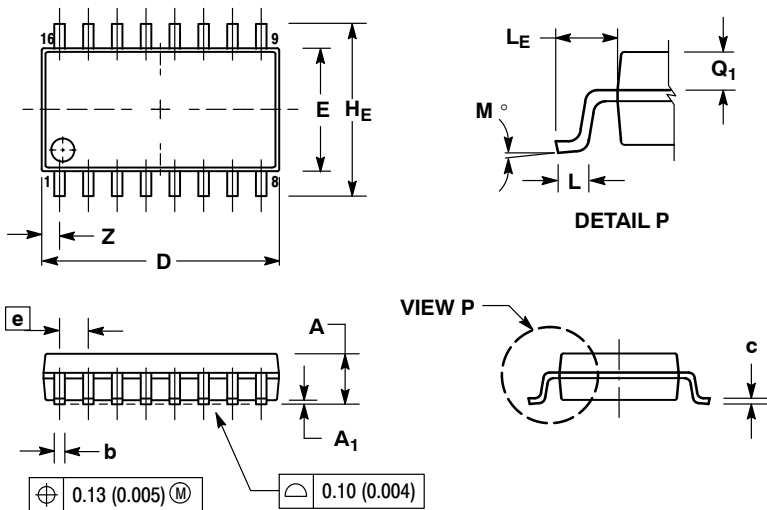


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SOEIAJ-16  
F SUFFIX  
PLASTIC EIAJ SOIC PACKAGE  
CASE 966-01  
ISSUE A



NOTES:

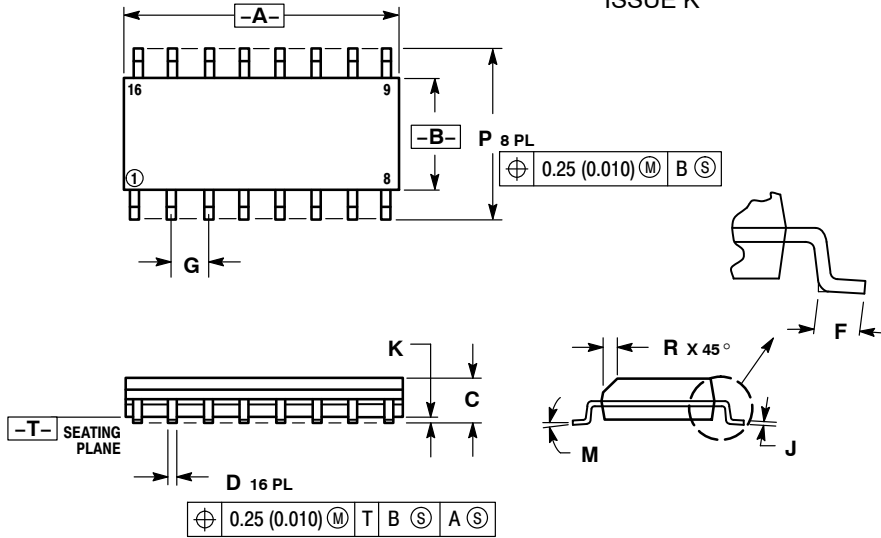
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H <sub>E</sub>	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L <sub>E</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

# MC14043B, MC14044B

## PACKAGE DIMENSIONS

SOIC-16  
D SUFFIX  
PLASTIC SOIC PACKAGE  
CASE 751B-05  
ISSUE K

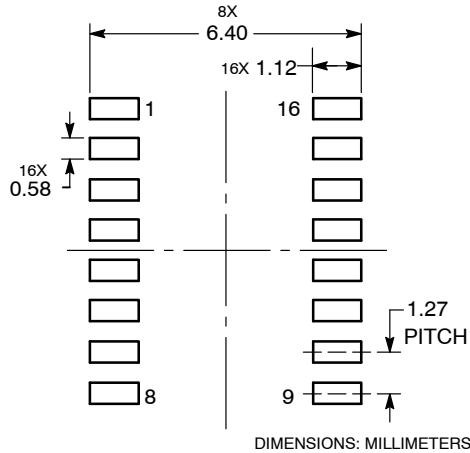


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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